

North America TC Chapter 3D Packaging & Integration (3DP&I) Global Technical Committee

Liaison Report | July 2021

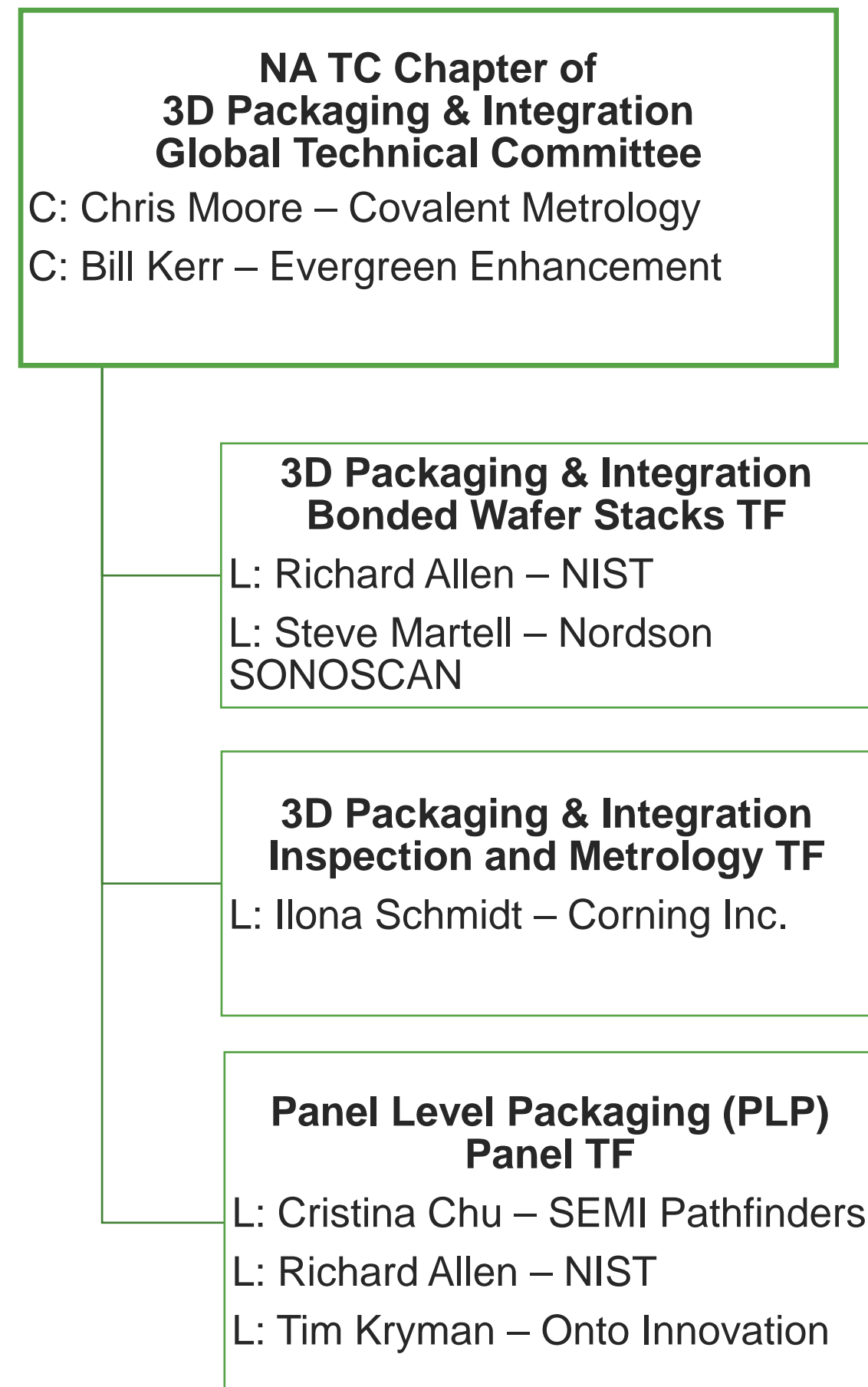
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Meeting Information

- Last meeting
 - Summer Meeting 2021
 - Thursday, July 15, 2021
 - via OVTCCM
- Next meeting
 - SEMICON West 2021
 - Schedule TBD

<http://www.semi.org/en/standards-events>

Organization Chart



Ballot Results [1/2]

| Doc # | Document Title | TC Chapter Action |
|-------|--|----------------------------------|
| R6641 | Revision to SEMI 3D8-0514, Guide for Describing Silicon Wafers for Use as 300 mm Carrier Wafers in a 3DS-IC Temporary Bond-Debond (TBDB) Process | Passed , A&R Cycle 7-2021 |
| 6810 | Reapproval of SEMI 3D13-0715, Guide for Measuring Voids in Bonded Wafer Stacks | Passed , as balloted |
| 6811 | Reapproval of SEMI 3D2-0216, Specification for Glass Carrier Wafers for 3DS-IC Applications | Passed , as balloted |
| 6812 | Reapproval of SEMI 3D4-0915, Guide for Metrology for Measuring Thickness, Total Thickness Variation (TTV), Bow, Warp/Sori, and Flatness of Bonded Wafer Stacks | Passed , as balloted |

#1: **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

#2: **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

Ballot Results [2/2]

| Doc # | Document Title | TC Chapter Action |
|-----------|---|---|
| SEMI 3D13 | SEMI 3D13-0715, Guide for Measuring Voids in Bonded Wafer Stacks <i>(Editorial Changes Type 2)</i> | Passed , to be submitted to ISC A&R SC |
| SEMI 3D2 | SEMI 3D2-0216, Specification for Glass Carrier Wafers for 3DS-IC Applications <i>(Editorial Changes Type 2)</i> | Passed , to be submitted to ISC A&R SC |
| SEMI 3D4 | SEMI 3D4-0915, Guide for Metrology for Measuring Thickness, Total Thickness Variation (TTV), Bow, Warp/Sori, and Flatness of Bonded Wafer Stacks <i>(Editorial Changes Type 2)</i> | Passed , to be submitted to ISC A&R SC |

#1: **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

#2: **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

Authorized Activities

| Doc # | Type | SC/TF/CFG | Document Title/Details |
|-------|-------|---------------------------|---|
| 6829 | SNARF | Bonded Wafer Stacks TF | Line Item Revision to SEMI 3D16-1116, Specification for Glass Base Material for Semiconductor Packaging |

Note 1: SNARFs and TFOFs are available for review on the SEMI Web site at:

<http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF>

Authorized Ballots

| Doc # | Type | SC/TF/CFG | Document Title/Details |
|-------|-------------------|------------------------|---|
| 6829 | Cycle 6 or 7-2021 | Bonded Wafer Stacks TF | Line Item Revision to SEMI 3D16-1116, Specification for Glass Base Material for Semiconductor Packaging |

Task Force Highlights



- Bonded Wafer Stacks TF and Inspection & Metrology TF met jointly
 - Reviewed Five-Year Review list and asked TC Chapter to authorize to ballot in Cycle 6 or 7-2021.
 - New topics for Fall 2021 meetings: cleaning of glass wafers, local flatness
- Panel Level Packaging (PLP) Panel TF
 - Reviewed SEMI 3D20, Specification for Panel Characteristics for Panel Level Packaging (PLP) Applications
 - TF met to discuss outcome of the SEMI 3D20 ballot
 - Target next TF meeting in 6-9 months
 - Will look at what optional parameters can be moved to Requirements section from Appendix 1

Thank you!

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